PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5799985

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKATOSHI KAMESHIMA	10/15/2019
HIDETO HASHIGUCHI	10/16/2019
IKUE MITSUHASHI	10/15/2019
HIROSHI HORIKOSHI	10/15/2019
REIJIROH SHOHJI	10/15/2019
MINORU ISHIDA	10/23/2019
TADASHI IIJIMA	10/18/2019
MASAKI HANEDA	10/29/2019

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO
Internal Address:	ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	243-0014

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16498739

CORRESPONDENCE DATA

Fax Number: (303)863-0223

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 303-863-9700
Email: sony@sheridanross.com
Correspondent Name: SHERIDAN ROSS P.C.
Address Line 1: 1560 BROADWAY
Address Line 2: SUITE 1200
Address Line 4: DENVER, COLORADO 80202-5141

ATTORNEY DOCKET NUMBER:	6810-1247
NAME OF SUBMITTER:	BRADLEY M. KNEPPER

SIGNATURE:	/Bradley M. Knepper/
DATE SIGNED:	11/01/2019

Total Attachments: 8
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Attorney Docket No.:
Sony Ref. No.: SP369537US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	**SOLID-STATE IMAGING DEVICE AND ELECTRONIC APPARATUS**

As the below named inventor, I hereby declare that:

This declaration is directed to:

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The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION, with offices at 4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

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And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: TAKATOSHI KAMESHIMA Date: October 15, 2019

Signature: Takatoshi Kameshima

Attorney Docket No.:
Sony Ref. No.: SP369537US00

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LEGAL NAME OF INVENTOR

Inventor: hideto hashiguchi
Date: October 16, 2019

Signature: Hideto Hashiguchi

Attorney Docket No.:
Sony Ref. No.: SP369537US00

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LEGAL NAME OF INVENTOR

Inventor: IKUE MITSUHASHI Date: October 15, 2019

Signature: Ikue Mitsuhashi

Attorney Docket No.:
Sony Ref. No.: SP369537US00

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LEGAL NAME OF INVENTOR

Inventor: HIROSHI HORIKOSHI Date: October 15, 2019

Signature: Hiroshi Horikoshi

Attorney Docket No.:
Sony Ref. No.: SP369537US00

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LEGAL NAME OF INVENTOR

Inventor: REIJIROH SHOHJI Date: 2019/10/15

Signature: Reijiroh Shohji

Attorney Docket No.:
Sony Ref. No.: SP369537US00

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LEGAL NAME OF INVENTOR

Inventor: MINORU ISHIDA

Date: October, 23, 2019

Signature: Minoru Ishida

Attorney Docket No.:
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LEGAL NAME OF INVENTOR

Inventor: tadashi iijima Date: 10/18/2019

Signature: Tadashi Iijima

Attorney Docket No.:
Sony Ref. No.: SP369537US00

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LEGAL NAME OF INVENTOR

Inventor: MASAKI HANEDA Date: Oct. 29th, 2019

Signature: Masaki Haneda